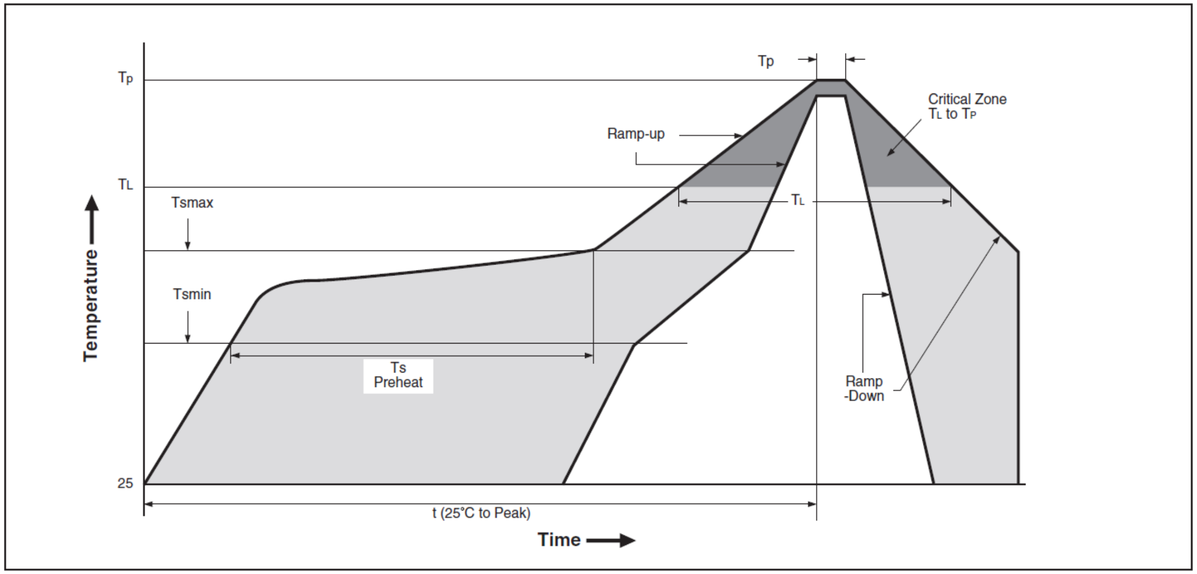
Reflow Soldering Conditions



Profile Feature		Soldering condition
Average Ramp-up Rate (T_L~T_P)		3℃ / second max.
Preheat	Temperature Min. ($T_{S\ min}$)	150℃
	Temperature Max. ($T_{S\ max}$)	200℃
	Time ($T_{S\ min}$~$T_{S\ max}$)	60~150 seconds
Ramp-up Rate ($T_{S\ max}$~T_L)		3℃ / second max.
Time maintained above	Temperature (T_L)	217℃
	Time (t_L)	60~90 seconds
Peak/classification Temperature (T_P)		250℃
Time within 5℃ of actual peak temperature		10 seconds max.
Ramp-Down Rate		3℃ / second max.
Time 25℃ to peak temperature		8 minutes max.

- Measured based on the temperature of the product.
- Reflow soldering conditions may be changed upon request.